

Notice of References Cited	Application/Control No. 09/846,707	Applicant(s)/Patent Under Reexamination KULA ET AL.	
	Examiner Brian E. Miller	Art Unit 2652	Page 1 of 1

U.S. PATENT DOCUMENTS

*		Document Number Country Code-Number-Kind Code	Date MM-YYYY	Name	Classification
	A	US-6,185,081	02-2001	Simion et al.	360/327.3
	B	US-6,222,707	04-2001	Huai et al.	360/324.1
	C	US-6,433,972	08-2002	Mao et al.	360/324.11
	D	US-6,490,140	12-2002	Mao et al.	360/324.11
	E	US-6,498,707	12-2002	Gao et al.	360/324.11
	F	US-6,507,457	01-2003	He et al.	360/126
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	L	US-			
	M	US-			

FOREIGN PATENT DOCUMENTS

*		Document Number Country Code-Number-Kind Code	Date MM-YYYY	Country	Name	Classification
	N					
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NON-PATENT DOCUMENTS

*		Include as applicable: Author, Title Date, Publisher, Edition or Volume, Pertinent Pages)
	U	IBM TDB, "Laminated Seed Layers for Plated Thin Film Heads and Structures", volume 35, issue 1B, pages 457-459, June 1, 1992.
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*A copy of this reference is not being furnished with this Office action. (See MPEP § 707.05(a).)
Dates in MM-YYYY format are publication dates. Classifications may be US or foreign.